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**TRANSMITTAL LETTER**  
**INFORMATION DISCLOSURE STATEMENT**

Applicant : Bogart et al.  
App. No : 10/816,340  
Filed : March 31, 2004  
For : MEANS TO IMPROVE CENTER-TO  
EDGE UNIFORMITY OF  
ELECTROCHEMICAL MECHANICAL  
PROCESSING OF WORKPIECE  
SURFACE  
Examiner : Calvin Lee  
Art Unit : 2825

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

March 7, 2005

(Date)

Tina Chen, Reg. No. 44,606

**Mail Stop Amendment**

Commissioner for Patents

P.O. Box 1450

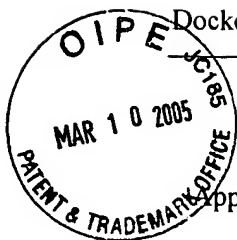
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified application are:

- (X) An Information Disclosure Statement and PTO/SB/08 equivalent listing references for consideration:
  - (X) Listing 52 references.
- (X) The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Account No. 11-1410.
- (X) Return prepaid postcard.

Tina Chen  
Registration No. 44,606  
Attorney of Record  
Customer No. 20,995  
(415) 954-4114



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Tina Chen, Reg. No. 44,606

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:


Enclosed is an Information Disclosure Statement by Applicant (PTO/SB/08 equivalent) listing 52 references that are of record in U.S. patent application No. 10/152,793, filed May 23, 2002 and U.S. patent application No. 09/511,278, filed February 23, 2000, which are parent applications of this continuation-in-part application, and is relied upon for an earlier filing date under 35 U.S.C. § 120. Copies of the references are not submitted pursuant to 37 C.F.R. § 1.98(d).

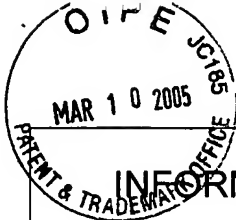
This Information Disclosure Statement is being filed before the receipt of a first Office Action on the merits, and presumably no fee is required. If a first Office Action on the merits was mailed before the mailing date of this Statement, the Commissioner is authorized to charge the fee set forth in 37 C.F.R. § 1.17(p) to Deposit Account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: March 7, 2005

By:   
Tina Chen  
Registration No. 44,606  
Attorney of Record  
Customer No. 20,995  
(415) 954-4114



# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Multiple sheets used when necessary)

SHEET 1 OF 3

Application No.	10/816,340
Filing Date	March 31, 2004
First Named Inventor	Bogart et al.
Art Unit	2825
Examiner	Calvin Lee
Attorney Docket No.	ASMNUT.2DVCP1

## U.S. PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
	1	1,739,657	12-1929	Shemitz	
	2	1,758,682	05-1930	Batenburg et al.	
	3	2,540,602	02-1951	Thomas et al.	
	4	3,328,273	06-1967	Creutz et al.	
	5	4,140,598	02-1979	Kimoto et al.	
	6	4,430,173	02-1984	Boudot et al.	
	7	4,948,474	08-1990	Miljkovic	
	8	4,954,142	09-1990	Carr et al.	
	9	4,975,159	12-1990	Dahms	
	10	5,084,071	01-1992	Nenadic et al.	
	11	5,256,565	10-1993	Bernhardt et al.	
	12	5,354,490	10-1994	Yu et al.	
	13	5,516,412	05-1996	Andricacos et al.	
	14	5,543,032	08-1996	Datta et al.	
	15	5,558,568	09-1996	Talieh et al.	
	16	5,681,215	10-1997	Sherwood et al.	
	17	5,755,859	05-1998	Brusic et al.	
	18	5,762,544	06-1998	Zuniga et al.	
	19	5,770,095	06-1998	Sasaki et al.	
	20	5,773,364	06-1998	Farkas et al.	
	21	5,793,272	08-1998	Burghartz et al.	
	22	5,795,215	08-1998	Guthrie et al.	
	23	5,807,165	09-1998	Uzoh et al.	
	24	5,840,629	11-1998	Carpio	
	25	5,858,813	01-1999	Scherber et al.	
	26	5,884,990	03-1999	Burghartz et al.	
	27	5,897,375	04-1999	Watts et al.	
	28	5,911,619	06-1999	Uzoh et al.	
	29	5,922,091	07-1999	Tsai et al.	

Examiner Signature

Date Considered

\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

T<sup>1</sup> - Place a check mark in this area when an English language Translation is attached.

<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  <i>(Multiple sheets used when necessary)</i>	Application No.	10/816,340
	Filing Date	March 31, 2004
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	Art Unit	2825
	Examiner	Calvin Lee
SHEET 2 OF 3	Attorney Docket No.	ASMNUT.2DVCP1

U.S. PATENT DOCUMENTS					
Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
	30	5,930,669	07-1999	Uzoh	
	31	5,933,753	08-1999	Simon et al.	
	32	5,954,997	09-1999	Kaufman et al.	
	33	5,985,123	11-1999	Koon	
	34	6,004,880	12-1999	Liu et al.	
	35	6,027,631	02-2000	Broadbent	
	36	6,063,506	05-2000	Andricacos et al.	
	37	6,066,030	05-2000	Uzoh	
	38	6,071,388	06-2000	Uzoh	
	39	6,074,544	06-2000	Reid et al.	
	40	6,103,085	08-2000	Woo et al.	
	41	6,132,578	10-2000	Jorne et al.	
	42	6,136,163	10-2000	Cheung et al.	
	43	6,176,992	01-2001	Talieh	
	44	6,217,426	04-2001	Tolles et al.	

FOREIGN PATENT DOCUMENTS						
Examiner Initials	Cite No.	Foreign Patent Document Country Code-Number-Kind Code Example: JP 1234567 A1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T <sup>1</sup>
	45	DE 43 24 330 A1	02-1994	Schneider et al.		
	46	EP 0 706 857 A1	04-1996	Talieh et al.		
	47	WO 98/27585	06-1998	Andricacos et al.		
	48	WO 00/26443	05-2000	Talieh		

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>1</sup>
	49	Chinese Office Action dated June 25, 2004, with English Translation.	
	50	KELLY et al., "Leveling and microstructural effects of additives for copper electrodeposition," <u>Journal of the Electrochemical Society</u> , 1999, pp. 2540-2545, Vol. 146, No. 7.	

Examiner Signature	Date Considered
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SHEET 3 OF 3	Attorney Docket No.	ASMNUT.2DVCP.1

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>1</sup>
	51	MIKKOLA et al., "Investigation of the roles of the additive components for second generation copper electroplating chemistries used for advanced interconnect metallization," <u>2000 IEEE</u> , June 2000, pp. 117-119, IEEE Electron Devices Society.	
	52	STEIGERWALD, et al., "Chemical mechanical planarization of microelectronic materials," 1997, pp. 212-222, A Wiley-Interscience Publication, by John Wiley & Sons.	

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